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Table of Contents

Preface, Committees

1. SURFACE PREPARATION FOR GATE DIELECTRIC WITH HIGH DIELECTRIC CONSTANT

High-k Gate Dielectrics on Silicon and Germanium: Impact of Surface Preparation
A. Beverina, M.M. Frank, H. Shang, S. Rivillon, F. Amy, C.L. Hsueh, V.K. Paruchuri, R.T. Mo, M. Copel, E.P. Gusev, M.A. Gribelyuk and Y.J. Chabal 3

UV Activated Surface Preparation of Silicon for High-k Dielectric Deposition
C.C. Finstad and A.J. Muscat 7

Enhanced Surface Preparation Techniques for the Si/High-k Interface
J. Barnett, C.D. Young, N. Moumen, G. Bersuker, J.J. Peterson, G.A. Brown, B.H. Lee and H.R. Huff 11

Uniform Ultrathin Oxide Growth for High-k Preclean
J.W. Butterbaugh, S.L. Nelson and T.J. Wagener 15

On the Application of a Thin Ozone Based Wet Chemical Oxide as an Interface for ALD High-k Deposition
B. Onsia, M. Caymax, T. Conard, S. De Gendt, F. De Smedt, A. Delabie, C. Gottschalk, M. Heyns, M. Green, S. Lin, P.W. Mertens, W. Tsai and C. Vinckier 19

Interface State Densities and Surface Charge on Wet-Chemically Prepared Si(100) Surfaces
H. Angermann 23

A Study of the Influence of Typical Wet Chemical Treatments on the Germanium Wafer Surface
B. Onsia, T. Conard, S. De Gendt, M. Heyns, I. Hoflijk, P.W. Mertens, M. Meuris, G. Raskin, S. Sioncke, I. Teerlinck, A. Theuwis, J. Van Steenbergen and C. Vinckier 27

Surface Preparation Techniques for High-k Deposition on Ge Substrates
S. Van Elshocht, A. Delabie, B. Brijs, M. Caymax, T. Conard, B. Onsia, R. Puurunen, O. Richard, J. Van Steenbergen, C. Zhao, M. Meuris and M. Heyns 31

2. FRONT-END-OF-LINE CLEANING, RINSE AND DRYING

Advanced Surface Cleaning Strategy for 65nm CMOS Device Performance Enhancement
F. Arnaud, H. Bernard, A. Beverina, R. El-Farhane, B. Duriez, K. Barla and D. Lévy 37

Process, Environmental & Economical Considerations to Implement Single Wafer Cleaning Tools in 300mm Wafer Fabs
P. Garnier, G. Horellou, J.J. Calvier, D. Labaty and D. Lévy 41

In Situ Wafer Processing for Next Generation Devices
I. Kashkoush, L. Liu, N. Yialamas and R. Novak 45

Organic Contamination Control in Silicon Surface Processing
K. Saga and T. Hattori 49

Application of UV/VIS-Spectroscopy for Determination of Complexing Agent Stability in APM and Like Mixtures Thereof
O. Doll and B.O. Kolbesen 55

Plasma Cleaning for W Polymetal Gate
A. Kabansky and H. Lee 59

Development of New Batch-Type Plasma Assisted NOR (Native-Oxide-Removal) Dry Cleaning Equipment
W.S. Kim, W.G. Hwang, I. Kim, K. Yun, K.M. Lee and S.K. Chae 63

Evaluation of Wafer Drying Methods for GIGA-LEVEL Device Fabrication
G.H. Kim, G.M. Choi and Y.W. Song 67

Surfactionated Rinse against Pattern Collapse and Defectivity in 193nm Lithography
S.I. Misat, G.G. Grozev and J.J. Versluijs 71

Performance of a Linear Single Wafer IPA Vapour Based Drying System
W. Fyen, S. Arnauts, F. Holsteyns, G. Doumen, G. Vereecke, J. Van Steenbergen and P.W. Mertens 75

Effective Rinse Aiming at Water-Mark-Free Drying for Single-Spin Wet Cleaning Process
K. Miya, T. Kishimoto and A. Izumi 79

Insights into Watermark Formation and Control
H. Namba, T. Orii, H. Ohno and G.W. Gale 83

Occurrence of Arsenic-Based Defects and Techniques for Their Elimination
F. Goh, C. Lim, V. Sih, Z. Ismail and S.Y.M. Chooi 87

3. WET AND GASEOUS ETCHING

Selective Wet Removal of Hf-Based Layers and Post-Dry Etch Residues in High-k and Metal Gate Stacks
M. Claes, V. Paraschiv, S. Beckx, M. Demand, W. Deweerd, S. Garaud, H. Kraus, R. Vos, J. Snow, W. Boullart and S. De Gendt 93

HF Based Solutions for HfO_2 Removal; Effect of pH and Temperature on HfO_2: SiO_2 Etch Selectivity
V. Paraschiv, M. Claes, M.R. Baklanov, W. Boullart, S. De Gendt and S. Vanhaelemeersch 97

Selective Si_3N_4 Etch in Single Wafer Application
D.M. Knotter, N. Stewart and I. Sharp 103

Etch Rate Depth Profiling by Single Wafer Etching Equipment
E. Bellandi, A.C. Elbaz, R. Piagge, F. Pipia and M. Alessandri 107

Novel Chemical Etching to Correct Film Thickness Distributions
H. Ugajin, H. Iwamoto and K. Kinoshita 111

Etching of Silicon Oxide Films in Supercritical Carbon Dioxide
K. Saga, H. Kuniyasu, T. Hattori, K. Yamada and T. Azuma 115

4. PARTICLES: CHALLENGE AND CLEANING METHODS

Challenges of Finer Particle Detection on Bulk-Silicon and SOI Wafers
T. Hattori, A. Okamoto and H. Kuniyasu 121

The Impact of Backside Particles on the Limits of Optical Lithography
T. Bearda, P.W. Mertens, F. Holsteyns, P. De Bisschop, R. Compen, A. van Meer and M. Heyns 129

Inspection Challenges at the 45nm Technology Node
D. Shortt and L. Cheung 133

Metrology and Removal of Nanoparticles from 500 Micron Deep Trenches
O. Guldiken, K. Bakhtari, A.A. Busnaina and J. Park 137

Evaluation of Megasonic Cleaning for Sub-90nm Technologies
G. Vereecke, F. Holsteyns, S. Arnauts, S. Beckx, P. Jaenen, K. Kenis, M. Lismont, M. Lux, R. Vos, J. Snow and P.W. Mertens 141

Strength Distribution of Megasonic Damage Events
K.K. Christenson 147

Using Megasonics for Particle and Residue Removal in Single Wafer Cleaning
S. Verhaverbeke, R. Gouk and D. Yost 151

Behaviour of a Well-Designed Megasonic Cleaning System
A. Lippert, P. Engesser, G. Ferrell, J. Klitzke, M. Köffler, F. Kumnig, J. Leberzammer, R. Obweger, A. Pfeuffer, H. Okorn-Schmidt and H. Sax 155

Megasonics: A Cavitation Driven Process
F. Holsteyns, K.T. Lee, S. Graf, R. Palmans, G. Vereecke and P.W. Mertens 159

Electrophoretic Studies on Silicon Nitride: Traces of Silicates in UPW Shift Zeta Potential Similar to SC-1
A. Pfeuffer, W. Bensch, A. Lechner and H. Okorn-Schmidt 163

Damage-Free Cleaning of Sub-50 nm Devices Using Directed Megasonics Technology in a Single Wafer Processor
J.J. Rosato, M.R. Yalamanchili, M.J. Beck and R.Y. Lillard 167

A Comparison of Particle Filtration in a Recirculated Wet Bench Wet Cleaning Tool: Performance of PTFE Filters and of Surface Optimized Filters
G. Haas, B. Parekh, J. Frankhauser, B. Viallet, P. Palka and J. Bras 171

5. PARTICLES: ALTERNATIVE CLEANING METHODS

Influences of Oxide Loss on Contamination Removal
A. Eitoku, J. Snow, R. Vos, K. Kenis and P.W. Mertens 177

Non-Damaging Particle Removal Using Cryogenic Aerosols
T.J. Wagener, J.F. Weygand and G.P. Thomes 181

Laser Cleaning of Particles from Silicon Wafers: Capabilities and Mechanisms
J. Graf, F. Lang, M. Mosbacher and P. Leiderer 185

Contaminants Removal from Epi Substrates Using Vapor-Laser Process
A. Wachs, S. Zeid, Y. Uziel, W. Huber and J. Krueger 189

Chemical Additive Formulations for Particle Removal in $SCCO_2$-Based Cleaning
M.B. Korzenski, D.D. Bernhard, T.H. Baum, K. Saga, H. Kuniyasu and T. Hattori 193

Non-Damaging CO_2 Aerosol Cleaning in FEOL IC Manufacturing
S. Banerjee and A. Campbell 199

Particle Adhesion on Tool Kit Part: Case Study for Ceramic Material
S. Blanc, B. Préauchat and M. Veillerot 203

6. METROLOGY

Simultaneous Analysis of Light and Heavy Organic Contamination on Silicon Wafer
H. Ritala, S. Eränen, A. Kiviranta, J. Räsänen, V. Tarkiainen, J. Kiuru and R.A. Ketola 209

VPD-DC-TXRF for Metallic Contamination Analysis of Ge Wafers
D. Hellin, V. Geens, I. Teerlinck, J. Van Steenbergen, J. Rip, W. Laureyn, G. Raskin, P.W. Mertens, S. De Gendt and C. Vinckier 213

Cu Spin Cleaning Evaluation by SOR X-Ray Fluorescence Analysis
H. Hayashi, K. Tsugane, Y. Kagoshima, T. Koyama, M. Watanabe and Y. Kozuki 217

Application of HPLC for the Analysis of Organic Additives in Cleaning Chemicals and Cleaning Mixtures
S. Metzger and B.O. Kolbesen 221

7. CONTAMINATION CONTROL

Chromium Contamination in Silicon: Detection and Impact on Oxide Performances
M.L. Polignano, D. Caputo, F. Cerutti, M. Cottini, L. Farini and J. Reffle 227

Further Reduction of Trace Level Ion from Ultra Pure Water and Its Effect on Electrical Property of Device
T. Umeda, S. Tsuzuki, R. Kokuun and K. Yoneda 233

Prevention of Copper Cross-Contamination on Cu Process and Non-Cu Process Mixed Fabrication
J.B. Shim, K.H. Lee, K.H. Kim and H.S. Park 237

Wafer Backside Cleaning Strategies for High-k/Metal Gate Processing
R. Vos, E. Kesters, S. Garaud, R. De Waele, K. Kenis, M. Lux, H. Kraus, J. Snow, D. Shamiryan, G. Catana, W. Deweerd, T. Schram, S. DeGendt and P.W. Mertens 241

Direct Mixing Cleaning Method of Aqua Regia on Wafer
H. Ugajin, H. Iwamoto and K. Kinoshita 245

Single Backside Cleaning on Silicon, Silicon Nitride and Silicon Oxide
L. Broussous, P. Besson, M.M. Frank and D. Bourgeat 249

The Degradation Prevention of Resin Materials for Semiconductor Manufacturing Equipment by Applying the Ultra-High Purity Gas Supply Technology
A. Hidaka, S. Yamashita, N. Tanahashi, H. Ishii, M. Kitano, Y. Shirai and T. Ohmi 255

Measurement and Control of Airborne Molecular Contamination during Wafer Storage and Transport
D. Alvarez, A. Tram and R.J. Holmes 259

Purification of Trace Amount of Metal Impurity from Ultra Pure Water Using Membrane Purifier/Filter
Y. Hashimoto, M. Amari, M. Komatsu and K. Fujiwara 265

Metal Contamination on Silicon Surfaces from Solvents
T. Bearda, I. Vander Mot, K. Van den Broeck, N. Van Hoornick, J. Van Hoeymissen and P.W. Mertens 269

8. POST CMP CLEANING

Adhesion and Removal of Alumina Slurry Particles on Wafer Surfaces in Cu CMP
Y.K. Hong, J.H. Han, J.H. Lee, J.G. Park and A.A. Busnaina 275

A Force Study in Brush Scrubbing
K.D. Xu, R. Vos, G. Vereecke, G. Doumen, W. Fyen, P.W. Mertens, M. Heyns, C. Vinckier and J. Fransaer 279

Dissolution Characteristics of Ceria in Ascorbic Acid Solutions with Implications to Cleaning
S. Tamilmani, V. Lowalekar, S. Raghavan and R. Small 283

Investigation of Dissolution and Electrodeposition of Copper in Concentrated and Diluted Oxalic Acid Media in Post-CMP Cleaning
C. Gabrielli, C. Mace, J. Matha, S. Mège, E. Ostermann and H. Perrot 287

Non-Contact Cleaning Process for Post-CMP Copper
D.A. Koos, J. Svirchevski, D.J. Vitkavage, D.G. Hansen, K.A. Reinhardt, F. Huang, M. Mitchel and G.Y. Zhang 291

9. WET PHOTO RESIST REMOVAL

Novel Photo Resist Stripping for Single Wafer Process
A. Okuyama, K. Asada, H. Abe, H. Iwamoto, Y. Okamoto and T. Wada 297

Resist Stripping for Advanced FEOL Nodes: Improvements to Process Based on Ozone Diffusion by Use of Additives
O. Louveau, E. Lajoinie, O. Pollet, J.P. Odet, S. Cêtre, L. Lachal, B. Icard, E. Tabouret, M. Veillerot, H. Fontaine and D. Louis 301

Cleaning Capability of High Concentration Ozonated Water
T. Haibara, K. Uemura and T. Adachi 305

Photoresist Stripping by Ozone/Water Processes: Effect of Additives
H. Vankerckhoven, F. De Smedt, K. Vandersmissen, M. Claes, S. De Gendt, M. Heyns and C. Vinckier 309

10. BACK-END-OF-LINE CLEANING

Supercritical CO$_2$ Applications in BEOL Cleaning
P.D. Matz and R.F. Reidy 315

Repair of Porous MSQ (p-MSQ) Films Using Monochlorosilanes Dissolved in Supercritical CO$_2$
B. Xie and A.J. Muscat 323

Copper Decontamination Ability of Supercritical-CO$_2$/Additives on CVD and Spin-On Porous MSQ Materials
J. Daviot, V. Perrut, F. Gaillard, C. Millet, A. Danel, L. Broussous and D. Louis 327

Angled XPS Analysis of Low-k Dielectric Surfaces after Cleaning
Y.S. Tan, S.Y.M. Chooi, C. Sin, P. Ee, M.P. Srinivasan and S.O. Pehkonen 331

Impact of Downstream Ash Plasmas on Ultra Low-k Materials
N. Posséme, T. David, P. Meininger, O. Louveau, T. Chevolleau, O. Joubert and D. Louis 337

Activated He:H$_2$ Strip of Photoresist over Porous Low-k Materials
Q.Y. Han, B. White, I.L. Berry, C. Waldfried and O. Escorcia 341

Qualification of Resist Strip Process for Ultra Low-k/Cu Interconnect
H. Xu, A. Shen, V. Tarasov, B. White and J. Wolf 345

Effect of Chemical Solution on the Stability of Low-k Films
E. Kesters, Q.T. Le, M.R. Baklanov, W. Boullart and P.W. Mertens 349

Aqueous Based Single Wafer Cu/Low-k Cleaning Process Characterization and Integration into Dual Damascene Process Flow
J.S. Tang, B.J. Brown, S. Verhaverbeke, H.W. Chen, J. Papanu, R. Hung, C. Cai and D. Yost 353

Via Cleaning Technology for Post Etch Residues
B.G. Sharma and C. Prindle 357

Barrier and Copper Seedlayer Wet Etching
C.T. Richard, M.M. Frank, P. Besson, E. Serret, N. Hotellier, A. Beverina, L. Dumas, L. Broussous, F. Kovacs and T. Billon 361

Deposition Behavior of Volatile Acidic Contaminants on Metallic Interconnect Surfaces
H. Fontaine, M. Veillerot and A. Danel 365

Effects of Patterns on Corrosion in Cu CMP
J.H. Han, J.E. Koo, D.H. Hong, B.L. Park, S.I. Kim, I. Cho, D.H. Eom, J.G. Park and A.A. Busnaina 369

Advanced Aqueous Cleaner II: PER Removal from Sensitive Cu/Low-k Devices
C. Reid, J. Daviot and D. Holmes 373

Advanced Aqueous Cleaner I, Dilute Solutions for the Selective Removal of Post Etch Residues in the Presence of Aluminium
J. Daviot, C. Reid and D. Holmes 377

New Post Etch Polymer Removal Process for Al-Interconnects and Vias in Tank and Spray Tools Using a New Inorganic Chemistry
R. Mellies, S. Kunz, F. Nilius, D. Mayer and A. Kühner 381

Effective Polymer Removal: Process Window-Process Uniformity-Extended Chemical Bath-Life
C. Yew-Leong, W. Boon-Lim, W. A-Cady, N. A-Mustapha and K. Keen-Lai 385